

Product / Process Change Notification



N° 2020-041-A

correction

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Dual flexible wafer manufacturing site strategy: expansion of several Gen 5 HVIC products produced at Newport Wafer Fab Limited

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before ~~1st April 2020~~. **4th March 2020**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

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► Products affected:

Please refer to attached affected product list 1_cip20041_a

► Detailed Change Information:

Subject: Enabling Newport Wafer Fab Limited for additional Gen 5 HVIC products

Reason: Expansion of current wafer production capacity to assure continuity of supply and enable flexible manufacturing.

Description:	<u>Old</u>	<u>New</u>
	Production Site Gen 5 HVIC technology released and in production at: <ul style="list-style-type: none">■ NXP Oak Hill■ Newport Wafer Fab Limited (previously announced to be decommissioned)	Gen 5 HVIC technology released and in production at: <ul style="list-style-type: none">■ NXP Oak Hill■ Newport Wafer Fab Limited will extend supply

► Product Identification:

Wafer fab origins will not be distinguished through the external part marking or shipping labels, however, based on the assembly lot code and marked on the device. IFX internal systems will be able to trace the site of the wafer lots used to produce the final product.

► Impact of Change:

No changes to form, fit or function. The package outline remains the same. Datasheet specifications will not be changed. The package bill of material and the location for assembly and final test will not change.

► Attachments:

Affected product list 1_cip20041_a

► Time Schedule:

- | | |
|-------------------------------|--------------|
| ■ Final qualification report: | upon Request |
| ■ First samples available: | upon Request |
| ■ Intended start of delivery: | 01-June-2020 |

If you have any questions, please do not hesitate to contact your local Sales office.